



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

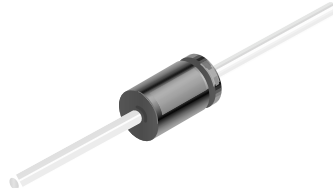
Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



# BAV19 / 20 / 21



**DO-35**

Color Band Denotes Cathode

## Small Signal Diode

### Absolute Maximum Ratings\*

$T_A = 25^\circ\text{C}$  unless otherwise noted

Symbol	Parameter	Value	Units
$V_{RRM}$	Maximum Repetitive Reverse Voltage	<b>BAV19</b>	120
		<b>BAV20</b>	200
		<b>BAV21</b>	250
$I_{F(AV)}$	Average Rectified Forward Current	200	mA
$I_{FSM}$	Non-repetitive Peak Forward Surge Current Pulse Width = 1.0 second Pulse Width = 1.0 microsecond	1.0	A
		4.0	A
$T_{stg}$	Storage Temperature Range	-65 to +200	$^\circ\text{C}$
$T_J$	Operating Junction Temperature	175	$^\circ\text{C}$

\* These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

**NOTES:**

- 1) These ratings are based on a maximum junction temperature of 200 degrees C.
- 2) These are steady state limits. The factory should be consulted on applications involving pulsed or low duty cycle operations.

### Thermal Characteristics

Symbol	Parameter	Value	Units
$P_D$	Power Dissipation	500	mW
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	300	$^\circ\text{C}/\text{W}$

### Electrical Characteristics

$T_A = 25^\circ\text{C}$  unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Max	Units
$V_R$	Breakdown Voltage	<b>BAV19</b> $I_R = 100 \mu\text{A}$	120		V
		<b>BAV20</b> $I_R = 100 \mu\text{A}$	200		V
		<b>BAV21</b> $I_R = 100 \mu\text{A}$	250		V
$V_F$	Forward Voltage	$I_F = 100 \text{ mA}$		1.0	V
		$I_F = 200 \text{ mA}$		1.25	V
$I_R$	Reverse Current	$V_R = 100 \text{ V}$		100	nA
		<b>BAV19</b> $V_R = 100 \text{ V}, T_A = 150^\circ\text{C}$		100	$\mu\text{A}$
		$V_R = 150 \text{ V}$		100	nA
		<b>BAV20</b> $V_R = 150 \text{ V}, T_A = 150^\circ\text{C}$		100	$\mu\text{A}$
		<b>BAV21</b> $V_R = 200 \text{ V}, T_A = 150^\circ\text{C}$		100	nA
$C_T$	Total Capacitance	$V_R = 0, f = 1.0 \text{ MHz}$		5.0	pF
$t_{rr}$	Reverse Recovery Time	$I_F = I_R = 30 \text{ mA}, I_{RR} = 3.0 \text{ mA}, R_L = 100\Omega$		50	ns

Typical Characteristics

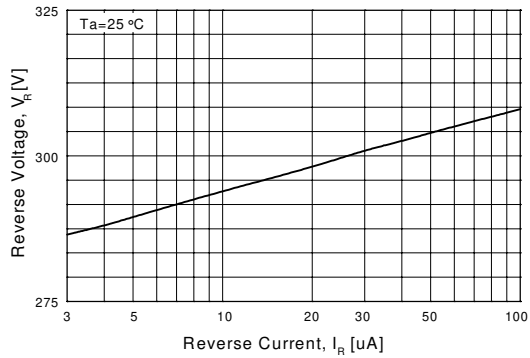


Figure 1. Reverse Voltage vs Reverse Current  
BV - 1.0 to 100uA

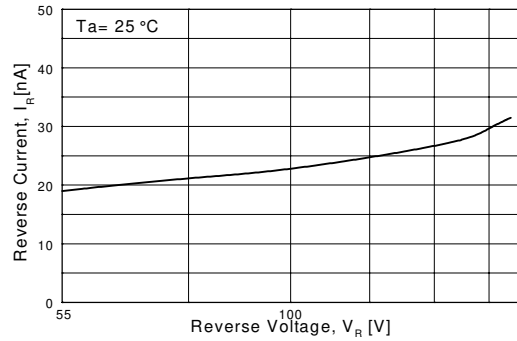


Figure 2. Reverse Current vs Reverse Voltage  
IR - 55 to 205 V  
GENERAL RULE: The Reverse Current of a diode will approximately double for every ten (10) Degree C increase in Temperature

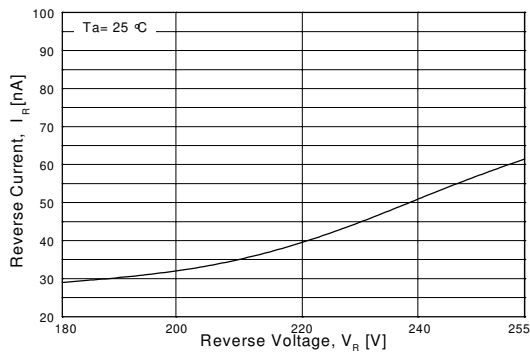


Figure 3. Reverse Current vs Reverse Voltage  
IR - 180 to 225 V  
GENERAL RULE: The Reverse Current of a diode will approximately double for every ten (10) Degree C increase in Temperature

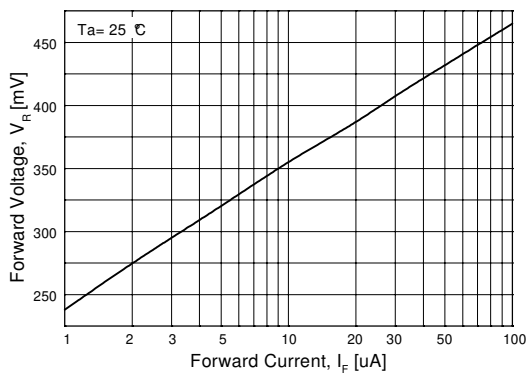


Figure 4. Forward Voltage vs Forward Current  
VF - 1.0 to 100uA

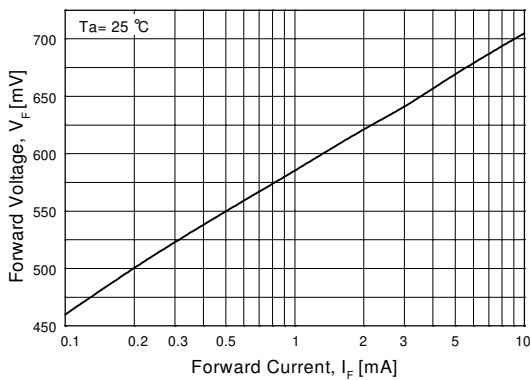


Figure 5. Forward Voltage vs Forward Current  
VF - 0.1 to 10mA

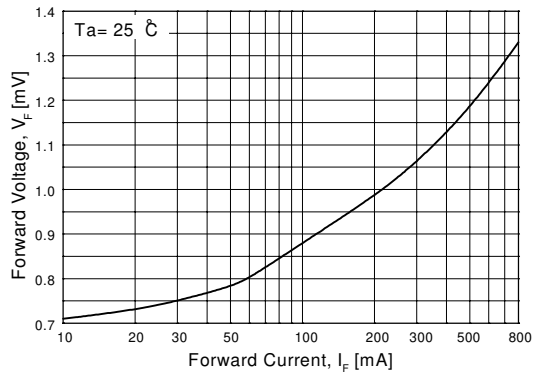


Figure 6. Forward Voltage vs Forward Current  
VF - 10 to 800mA

Typical Characteristics (continued)

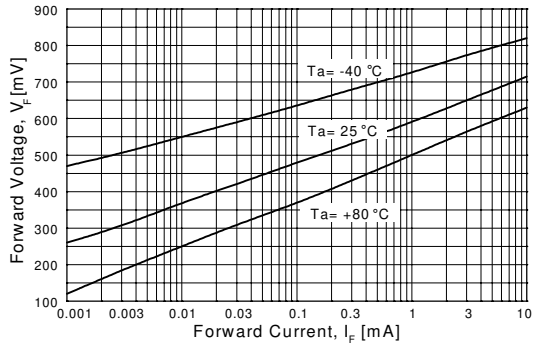


Figure 7. Forward Voltage vs Ambient Temperature  
VF - 1.0 uA - 10 mA (-40 to +80 Deg C)

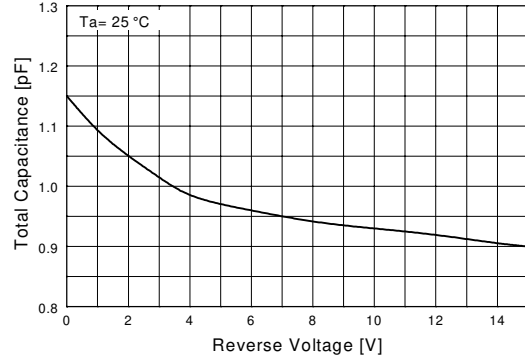


Figure 8. Total Capacitance

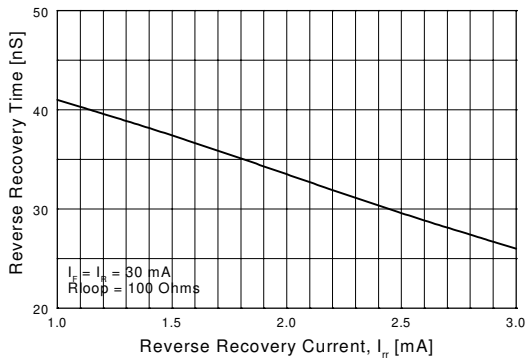


Figure 9. Reverse Recovery Time vs Reverse Recovery Current

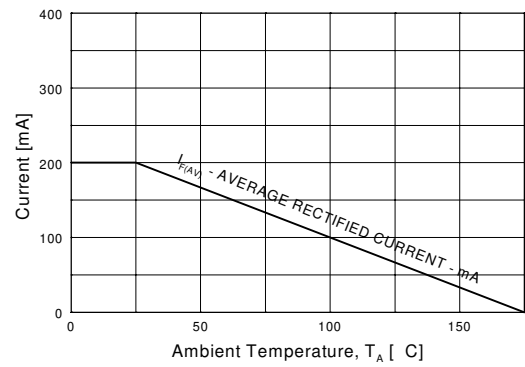


Figure 10. Average Rectified Current ( $I_{F(AV)}$ ) versus Ambient Temperature ( $T_A$ )

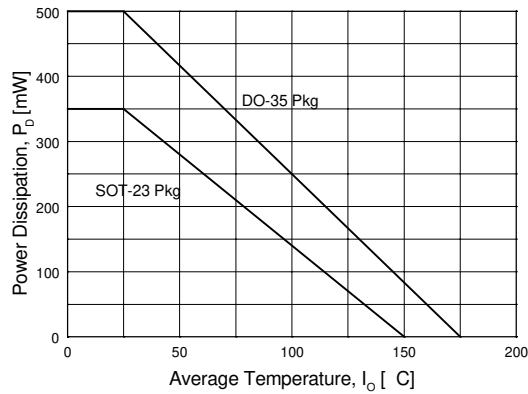


Figure 11. Power Derating Curve

## TRADEMARKS

The following are registered and unregistered trademarks Fairchild Semiconductor owns or is authorized to use and is not intended to be an exhaustive list of all such trademarks.

ACE <sub>x</sub> <sup>™</sup>	FAST <sup>®</sup>	OPTOLOGIC <sup>™</sup>	SMART START <sup>™</sup>	VCX <sup>™</sup>
Bottomless <sup>™</sup>	FAST <sub>r</sub> <sup>™</sup>	OPTOPLANAR <sup>™</sup>	STAR*POWER <sup>™</sup>	
CoolFET <sup>™</sup>	FRFET <sup>™</sup>	PACMAN <sup>™</sup>	Stealth <sup>™</sup>	
CROSSVOLT <sup>™</sup>	GlobalOptoisolator <sup>™</sup>	POP <sup>™</sup>	SuperSOT <sup>™</sup> -3	
DenseTrench <sup>™</sup>	GTO <sup>™</sup>	Power247 <sup>™</sup>	SuperSOT <sup>™</sup> -6	
DOMET <sup>™</sup>	HiSeC <sup>™</sup>	PowerTrench <sup>®</sup>	SuperSOT <sup>™</sup> -8	
EcoSPARK <sup>™</sup>	ISOPLANAR <sup>™</sup>	QFET <sup>™</sup>	SyncFET <sup>™</sup>	
E <sup>2</sup> CMOS <sup>™</sup>	LittleFET <sup>™</sup>	QS <sup>™</sup>	TinyLogic <sup>™</sup>	
EnSigna <sup>™</sup>	MicroFET <sup>™</sup>	QT Optoelectronics <sup>™</sup>	TruTranslation <sup>™</sup>	
FACT <sup>™</sup>	MicroPak <sup>™</sup>	Quiet Series <sup>™</sup>	UHC <sup>™</sup>	
FACT Quiet Series <sup>™</sup>	MICROWIRE <sup>™</sup>	SILENT SWITCHER <sup>®</sup>	UltraFET <sup>®</sup>	

STAR\*POWER is used under license

## DISCLAIMER

FAIRCHILD SEMICONDUCTOR RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION OR DESIGN. FAIRCHILD DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS.

## LIFE SUPPORT POLICY

FAIRCHILD'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF FAIRCHILD SEMICONDUCTOR CORPORATION.

As used herein:

1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, or (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in significant injury to the user.
2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

## PRODUCT STATUS DEFINITIONS

### Definition of Terms

Datasheet Identification	Product Status	Definition
Advance Information	Formative or In Design	This datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
Preliminary	First Production	This datasheet contains preliminary data, and supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design.
No Identification Needed	Full Production	This datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design.
Obsolete	Not In Production	This datasheet contains specifications on a product that has been discontinued by Fairchild semiconductor. The datasheet is printed for reference information only.